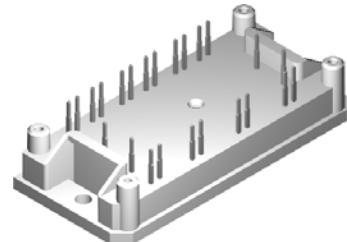
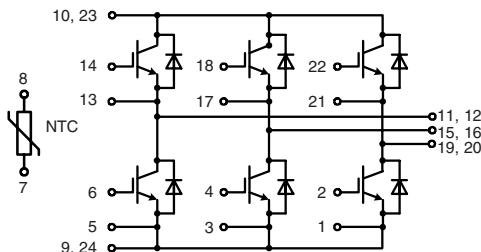


IGBT Module**Sixpack**

Short Circuit SOA Capability
Square RBSOA

I_{C25} = 43 A
V_{CES} = 1200 V
V_{CE(sat)} typ. = 1.9 V

**IGBTs**

Symbol	Conditions	Maximum Ratings		
V _{CES}	T _{VJ} = 25°C to 150°C	1200		V
V _{GES}		± 20		V
I _{C25}	T _C = 25°C	43		A
I _{C80}	T _C = 80°C	31		A
I _{CM}	V _{GE} = ±15 V; R _G = 36 Ω; T _{VJ} = 125°C	50		A
V _{CEK}	RBSOA; clamped inductive load; L = 100 μH		V _{CES}	
t _{sc}	V _{CE} = 900 V; V _{GE} = ±15 V; R _G = 36 Ω; T _{VJ} = 125°C	10		μs
SCSOA; non-repetitive				
P _{tot}	T _C = 25°C	160		W

Symbol	Conditions	Characteristic Values		
		(T _{VJ} = 25°C, unless otherwise specified)		
		min.	typ.	max.
V _{CE(sat)}	I _C = 25 A; V _{GE} = 15 V; T _{VJ} = 25°C T _{VJ} = 125°C	1.9	2.3	V
		2.2		V
V _{GE(th)}	I _C = 1 mA; V _{GE} = V _{CE}	4.5		V
I _{CES}	V _{CE} = V _{CES} ; V _{GE} = 0 V; T _{VJ} = 25°C T _{VJ} = 125°C		0.4	mA
			0.6	mA
I _{GES}	V _{CE} = 0 V; V _{GE} = ± 20 V		400	nA
t _{d(on)} t _r t _{d(off)} t _f E _{on} E _{off}	Inductive load, T _{VJ} = 125°C V _{CE} = 600 V; I _C = 25 A V _{GE} = ±15 V; R _G = 36 Ω	90		ns
		50		ns
		520		ns
		90		ns
		2.5		mJ
		3.4		mJ
C _{ies}	V _{CE} = 25 V; V _{GE} = 0 V; f = 1 MHz	1810		pF
Q _{Gon}	V _{CE} = 600 V; V _{GE} = 15 V; I _C = 25 A	240		nC
R _{thJC}	(per IGBT)		0.8	K/W
R _{thCH}		0.3		K/W

Features

- Trench IGBTs
 - low saturation voltage
 - positive temperature coefficient for easy paralleling
 - fast switching
 - short tail current for optimized performance also in resonant circuits
- HiPerFRED™ diode:
 - fast reverse recovery
 - low operating forward voltage
 - low leakage current
- Industry Standard Package
 - solderable pins for PCB mounting
 - isolated copper base plate

Typical Applications

- AC drives
- power supplies with power factor correction

Diodes

Symbol	Conditions	Maximum Ratings		
I _{F25}	T _C = 25°C	49	A	
I _{F80}	T _C = 80°C	32	A	

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
V _F	I _F = 25 A; V _{GE} = 0 V; T _{VJ} = 25°C T _{VJ} = 125°C	2.4 1.6	2.7 V	V
I _{RM} t _{rr}	I _F = 25 A; dI _F /dt = -600 A/μs; T _{VJ} = 100°C V _R = 600 V; V _{GE} = 0 V	25 150	A ns	
R _{thJC} R _{thCH}	(per diode)	0.3	0.9 K/W K/W	

Temperature Sensor NTC

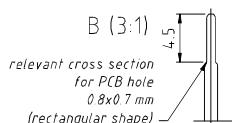
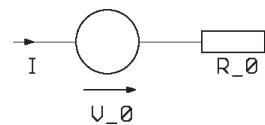
Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
R ₂₅	T = 25°C	4.45	4.7	5.0 kΩ
B _{25/85}			3510	K

Module

Symbol	Conditions	Maximum Ratings		
T _{VJ}	operating	-40...+125	°C	
T _{VJM}		-40...+150	°C	
T _{stg}		-40...+125	°C	
V _{ISOL}	I _{ISOL} ≤ 1 mA; 50/60 Hz	2500	V~	
M _d	Mounting torque (M4)	2.0 - 2.2	Nm	

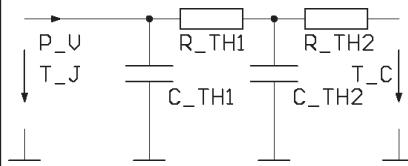
Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
d _s	Creepage distance on surface	12.7		mm
d _A	Strike distance in air	12.7		mm

Weight	40	g
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**Equivalent Circuits for Simulation****Conduction**

IGBT (typ. at V_{GE} = 15 V; T_J = 125°C)
V₀ = tbd; R₀ = tbd

Free Wheeling Diode (typ. at T_J = 125°C)
V₀ = 1.6 V; R₀ = 13 mΩ

Thermal Response

IGBT (typ.)

C_{th1} = tbd J/K; R_{th1} = tbd K/W
C_{th2} = tbd J/K; R_{th2} = tbd K/W

Free Wheeling Diode (typ.)

C_{th1} = tbd J/K; R_{th1} = tbd K/W
C_{th2} = tbd J/K; R_{th2} = tbd K/W

Dimensions in mm (1 mm = 0.0394")